

Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

1. (Currently amended) A method for conditioning semiconductor wafers and/or hybrids ~~having the steps comprising:~~

preparing a space which is essentially enclosed by a container and has a wafer/hybrid ~~holding device~~ chuck which is located therein and has the purpose of holding a semiconductor wafer and/or hybrid applied to the wafer/hybrid chuck;

pre-cooling a dry fluid in a heat~~[-]~~ exchanger outside the space;

conducting the pre-cooled fluid ~~from out of~~ into the heat exchanger into the wafer/hybrid ~~holding device~~ chuck via a first line, and then through the wafer/hybrid ~~holding device~~ chuck to cool the wafer/hybrid ~~holding device~~ chuck;

conducting at least a portion of the fluid having ~~left been conducted through~~ been conducted through the wafer/hybrid ~~holding device~~ chuck to the heat exchanger via a second line out of the wafer/hybrid chuck to the heat exchanger; and

heating the portion, by using a residual coldness of the portion ~~for~~ to cool the heat exchanger to contribute to the pre-cooling of the fluid in the heat exchanger;

wherein the heated portion is conducted via a third line from the heat exchanger into the space ~~via a third line~~, before being allowed to flow out within the space to condition the atmosphere in the space.

2. (Cancelled).

3. (Currently amended) The method according to Claim 1, ~~characterized in that~~
wherein the portion is firstly heat-treated and then allowed to flow out within the space.

4. (Currently amended) The method according to Claim 1, ~~characterized in that~~
wherein the portion is heat-treated outside the space and then fed back to the space.

5. (Currently amended) The method according to Claim 1, ~~characterized in that~~
wherein the portion is allowed to flow out within the space directly after it leaves the
wafer/hybrid ~~holding device~~ chuck.

6. (Currently amended) A method for conditioning semiconductor wafers
and/or hybrids ~~having the steps comprising:~~

preparing a space which is essentially enclosed by a container and has a
wafer/hybrid ~~holding device~~ chuck which is located therein and has the purpose of
holding a semiconductor wafer and/or hybrid applied to the wafer/hybrid chuck;

pre-cooling a dry fluid in a heat[[-]]_exchanger outside the space;

conducting the pre-cooled fluid ~~from~~ out of the heat exchanger into the
wafer/hybrid ~~holding device~~ chuck via a first line, and then through the wafer/hybrid
~~holding device~~ chuck to cool the wafer/hybrid ~~holding device~~ chuck;

wherein at least a portion of the fluid having ~~left~~ been conducted through the
wafer/hybrid ~~holding device~~ chuck is used to condition the atmosphere within the space;

wherein a first portion of the fluid having ~~left~~ been conducted through the
wafer/hybrid ~~holding device~~ chuck is firstly conducted via a second line out of the

wafer/hybrid chuck to the heat exchanger ~~via a second line~~, then heated by using a residual coldness of the first portion to cool the heat exchanger to contribute to the pre-cooling of the fluid in the heat exchanger ~~outside the space~~, and then conducted ~~back into the space~~ via a third line from the heat exchanger into the space, before being allowed to flow out within the space, and

wherein a second portion having been conducted through the wafer/hybrid chuck is allowed to flow out within the space directly after it leaves the wafer/hybrid ~~holding device~~ chuck[[;]].

~~wherein the first portion is heated by being used for the pre-cooling of the fluid in the heat exchanger, before being allowed to flow out within the space.~~

7. (Currently amended) The method according to Claim 6, ~~characterized in that~~ wherein at least one of the first and second portions can be regulated in terms of flow rate.

8. (Currently amended) The method according to Claim 3, ~~characterized in that~~ wherein the portion is heat-treated in that it is used for precooling the fluid, outside the space before said portion is allowed to flow out within the space.

9. (Withdrawn) A device for conditioning semiconductor wafers and/or hybrids having:

space being at least partially enclosed by a container and having a wafer/hybrid holding device which is located therein and has the purpose of holding a semiconductor wafer and/or hybrid;

a first line via which the fluid can be conducted into the container and into the wafer/hybrid holding device from outside the space;

a second line via which the fluid can be conducted from the wafer/hybrid holding device to outside the space; and

a third line via which at least a portion of the fluid can be fed back from outside the space into the space for conditioning the atmosphere within the space.

10. (Withdrawn) The device according to Claim 9, characterized in that the line device has:

wherein a temperature regulating device is provided between the second and third lines.

11. (Withdrawn) The device according to Claim 10, characterized in that outflow elements are provided at the end of the third line.

12. (Withdrawn) The device according to Claim 9, further comprising a fourth line via which the fluid can be conducted from the wafer/hybrid holding device into the space.

13. (Cancelled)

14. (Withdrawn) The device according to Claim 12, characterized in that a valve is provided for regulating the flow rate of the fourth line.

15. (Withdrawn) The device according to Claim 10, characterized in that the temperature regulating device has a heating device.

16. (Withdrawn) The device according to Claim 10, characterized in that the temperature regulating device has a heat exchanger to which at least a portion of the fluid leaving the space can be conducted.

17. (Withdrawn) The device according to Claim 16, characterized in that the heat exchanger is used to precool the fed-in fluid.

18. (Withdrawn) The device according to Claim 16, wherein the portion leaving the heat exchanger can be fed back at least partially into the space in order to condition the atmosphere.

19. (Withdrawn) The device according to Claims 9, characterized in that a further line is provided via which dry fluid can additionally be conducted directly into the space from outside the space.

20. (Cancelled).

21. (Withdrawn) A method for conditioning semiconductor wafers and/or hybrids having the steps:

preparing a space which is at least partially enclosed and has a wafer/hybrid holding device which is located therein and has the purpose of holding a semiconductor wafer and/or hybrid;

conducting a dry fluid into the space and through the wafer/hybrid holding device in order to heat-treat the wafer/hybrid holding device;

conducting said fluid from the wafer/hybrid holding device to outside the space;

wherein at least a portion of the fluid which has been conducted from the wafer/hybrid holding device to outside the space is used to condition the atmosphere within the space by being conducted back into the space.

22. (New) The method according to Claim 1, wherein the pre-cooled fluid, when conducted through the wafer/hybrid chuck in order to cool the wafer/hybrid chuck, crosses the wafer/hybrid chuck in a cooling coil or cooling pipe.

23. (New) The method according to Claim 6, wherein the pre-cooled fluid, when conducted through the wafer/hybrid chuck in order to cool the wafer/hybrid chuck, crosses the wafer/hybrid chuck in a cooling coil or cooling pipe.